

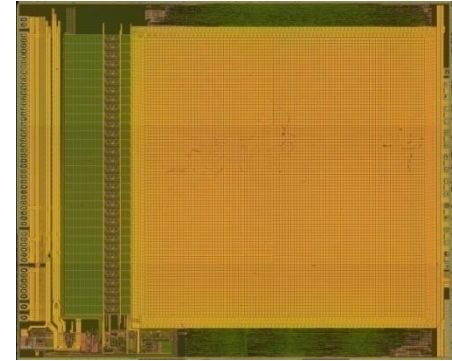
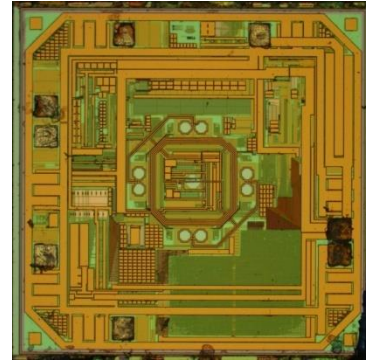
MEIZU MX4 Pro M462

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Teardown Analysis Report

MEIZU MX4 Pro M462 Product Analysis Report

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